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KIM et al.(10) **Pub. No.: US 2022/0353999 A1**(43) **Pub. Date: Nov. 3, 2022**(54) **SYSTEM AND METHOD FOR
MANUFACTURING COMPOSITE BOARD**(30) **Foreign Application Priority Data**

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(KR)(57) **ABSTRACT**(21) Appl. No.: **17/622,551**(22) PCT Filed: **Jun. 25, 2020**(86) PCT No.: **PCT/KR2020/008270**

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A system for manufacturing a printed circuit board includes a coverlay supply apparatus configured to supply a coverlay; a printed circuit board supply apparatus configured to supply a printed circuit board; and a pre-bonding apparatus configured to pre-bond the coverlay supplied from the coverlay supply apparatus onto the printed circuit board supplied from the printed circuit board supply apparatus, thereby discharging a first composite board.

